

MULTI-BEAM CARD EDGE CONNECTORS

TE Connectivity's (TE) next generation MULTI-BEAM card edge connectors deliver the best overall power and signal density to address server market requirements for performance, profile and cost. MULTI-BEAM card edge connectors are also applicable in global data communication applications to decrease costs.

These products are the next generation card edge connectors over the current SEC-II power card edge products and deliver superior current and signal density with a unique design.

The scalable and modular features also support greater flexibility in configuration and PCB design.

KEY BENEFITS

- High density
- Better connectivity tolerance
- Modular design
- Better performance

APPLICATIONS

- Data center
- Telecommunications
- · Industrial automation devices
- Power systems

PRODUCT FEATURES & BENEFITS

High Density

- Highest signal density in the market with 60% signal space savings
- 30% power density improvement over legacy products
- Smaller pitch: signal pitch 1.00mm, power pitch 7.26mm
- Greater power contact, max. 43A

Better Connectivity Tolerance

- Better gatherability for blind-mate applications: +/-2.0mm (X), +/-1.54mm (Y)
- More clearance between PCB pads for signal contact to prevent solder bridging, and 1.3mm larger pads for easier alignment
- Support two PCB thickness: 1.57mm and 2.36mm

Modular Design

- Common power and signal contact module
- Flexible configuration with different contact quantities and positions
- Better scalability (AC & DC, low power & high power)

Better Performance

- Excellent mechanical and electrical performance
- Easy mating/un-mating with proper retention force
- · Low level contact resistance

PRODUCT CONFIGURATIONS



Vertical



Straddle



Right Angle

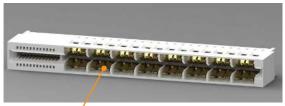
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ORDERING INFORMATION

Signal 2x4
2x4
2x24
2x12
2x4
2x5
2x4
2x24
2x4
2x24
2x6
2x6



Signal - up to 60% space savings



Power - up to 30% space savings

Specifications

- Current rating:
 - Power contact: up to 43A
 - Signal contact: up to 2A
- Voltage rating:
 - Power: 100V max.
 - Signal: 60V max.
- Durability: 200 mating cycles
- Mechanical shock: EIA-364-27
- Vibration: EIA-364-28
- Operating temperature: -55°C to 105°C
- Low mating force
 - 6N max. per power contact
 - 1.5N max. per signal contact
- PCB thickness: 1.57mm and 2.36mm
- Material: high conductivity copper alloy and high temperature resin with RoHS compliance
- Product spec: 108-32043
- Application spec: 114-128016

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